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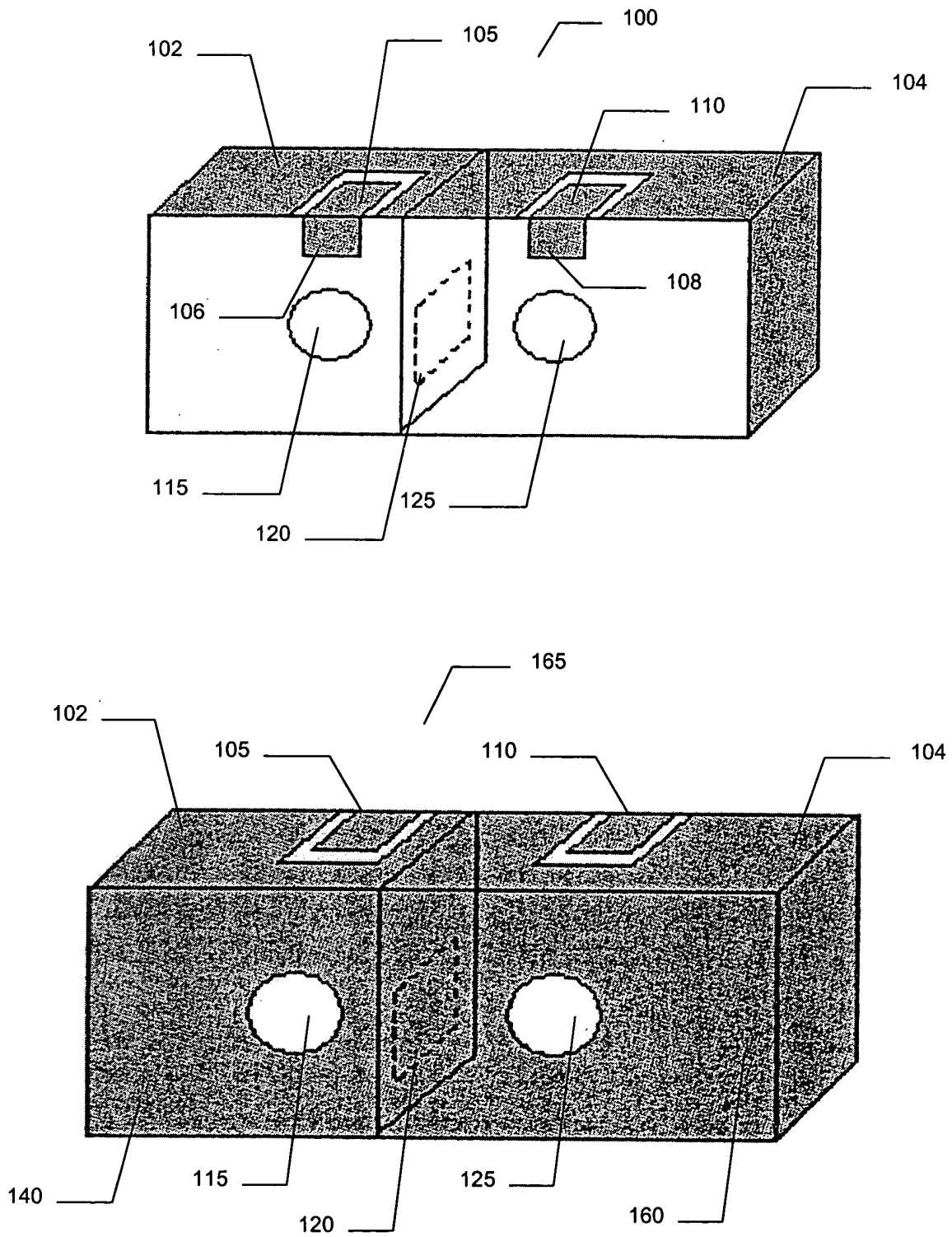
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**FIGURE 1**



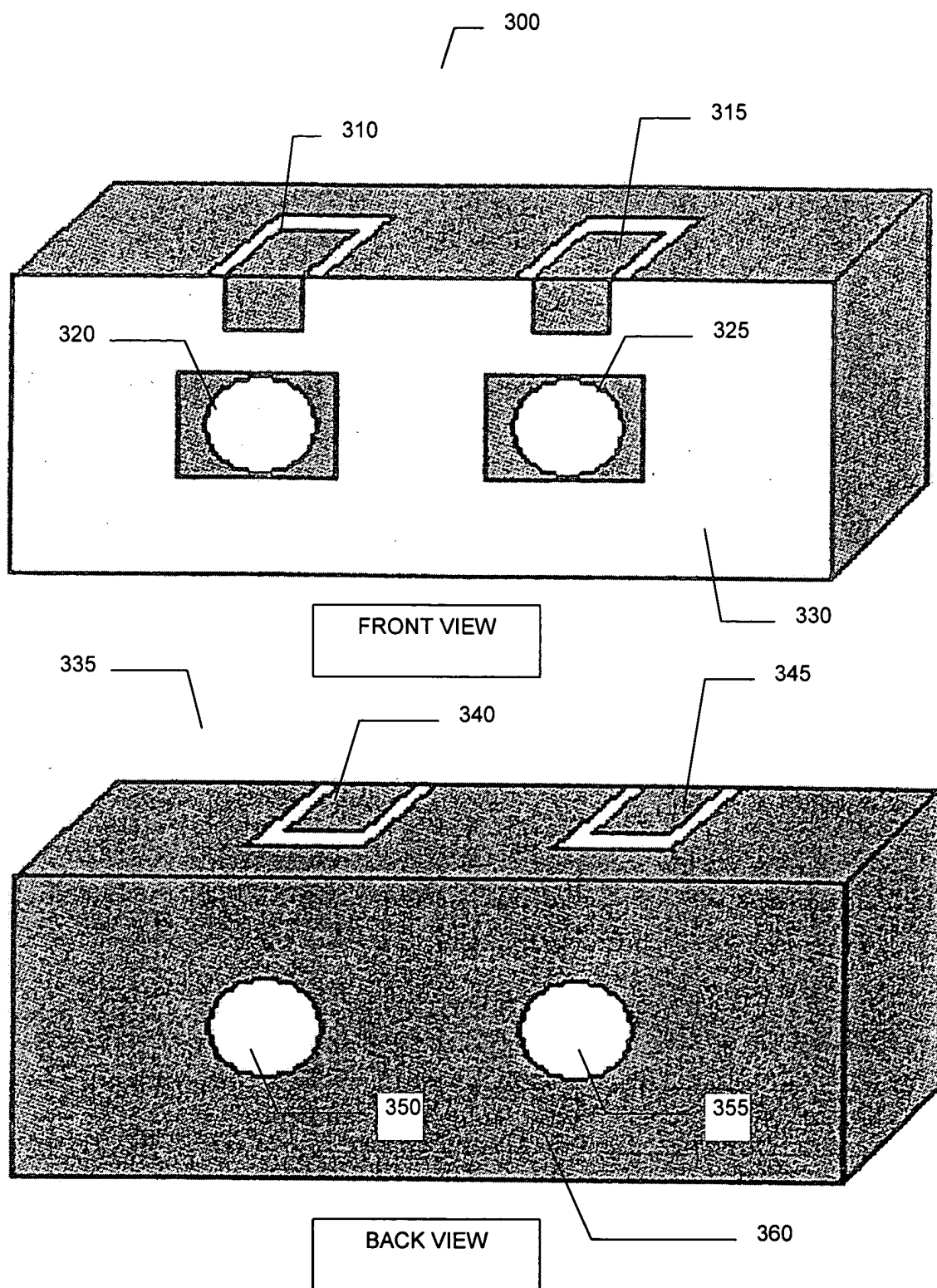


FIGURE 3

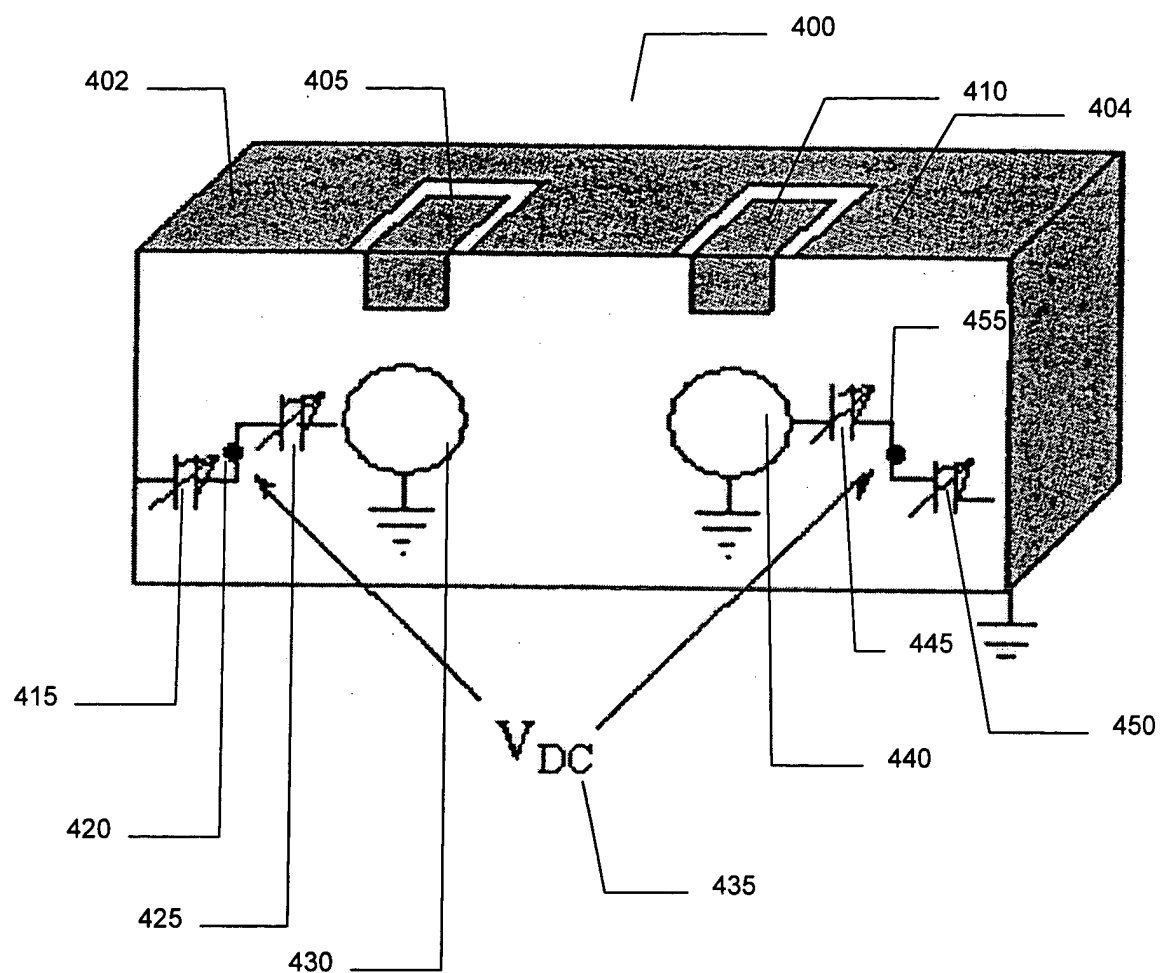


FIGURE 4

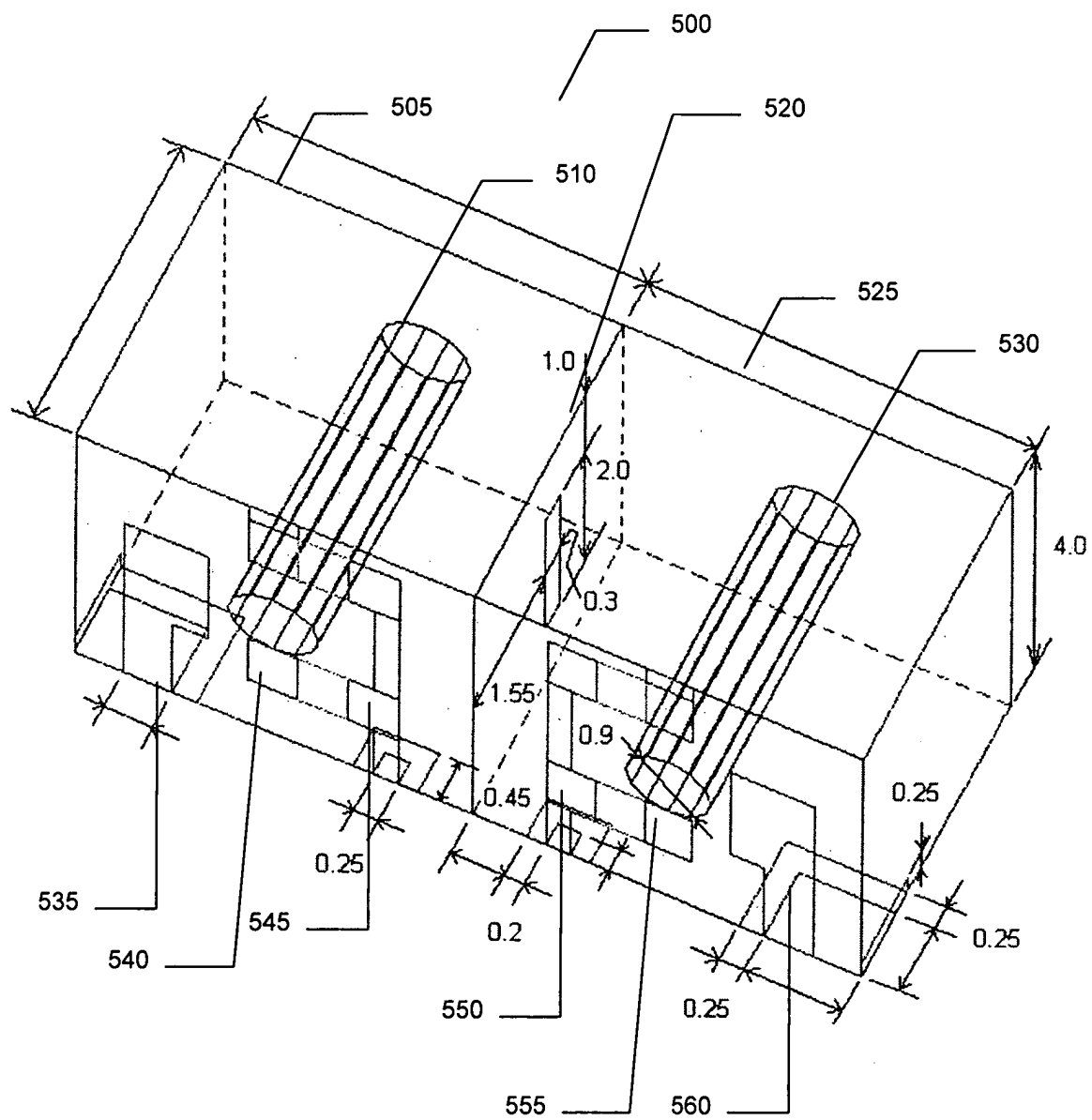


FIGURE 5

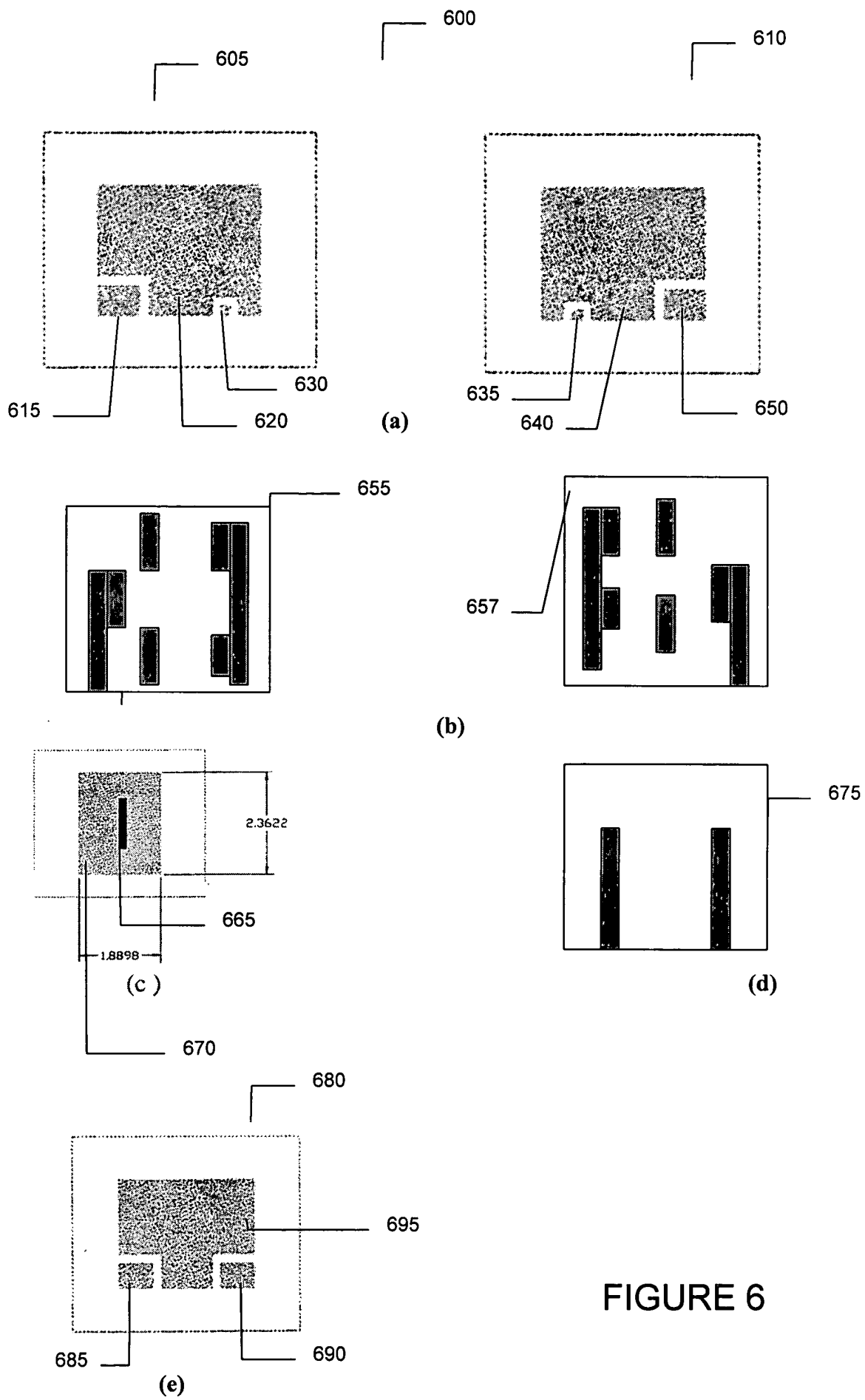


FIGURE 6

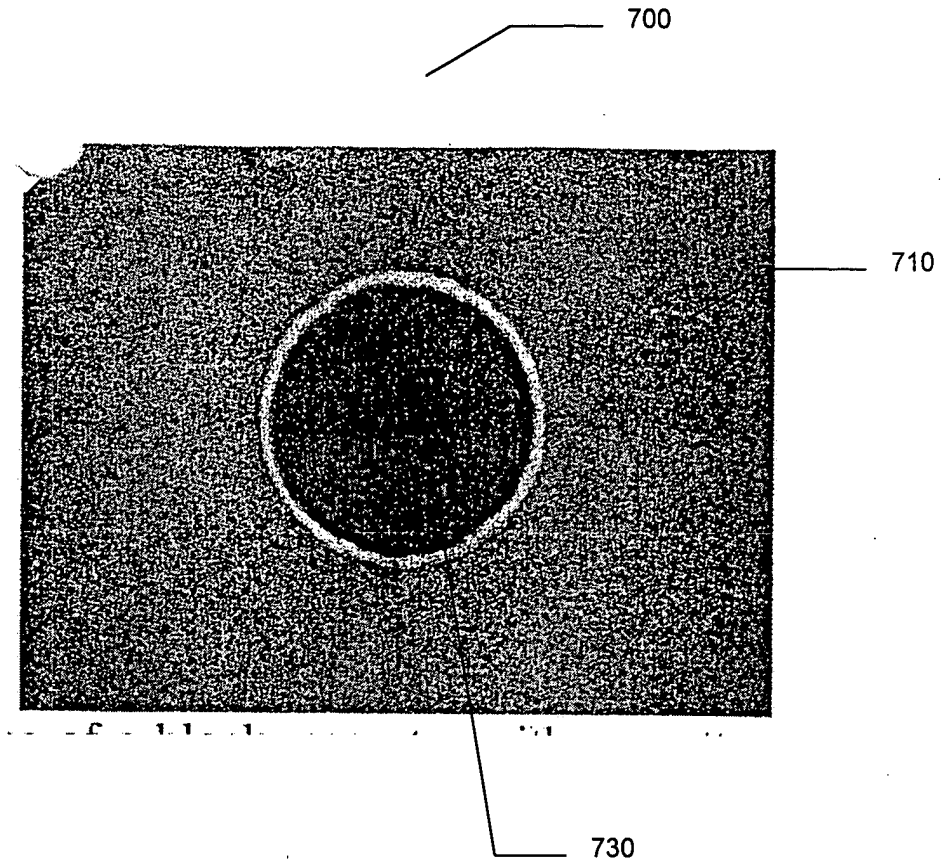


FIGURE 7



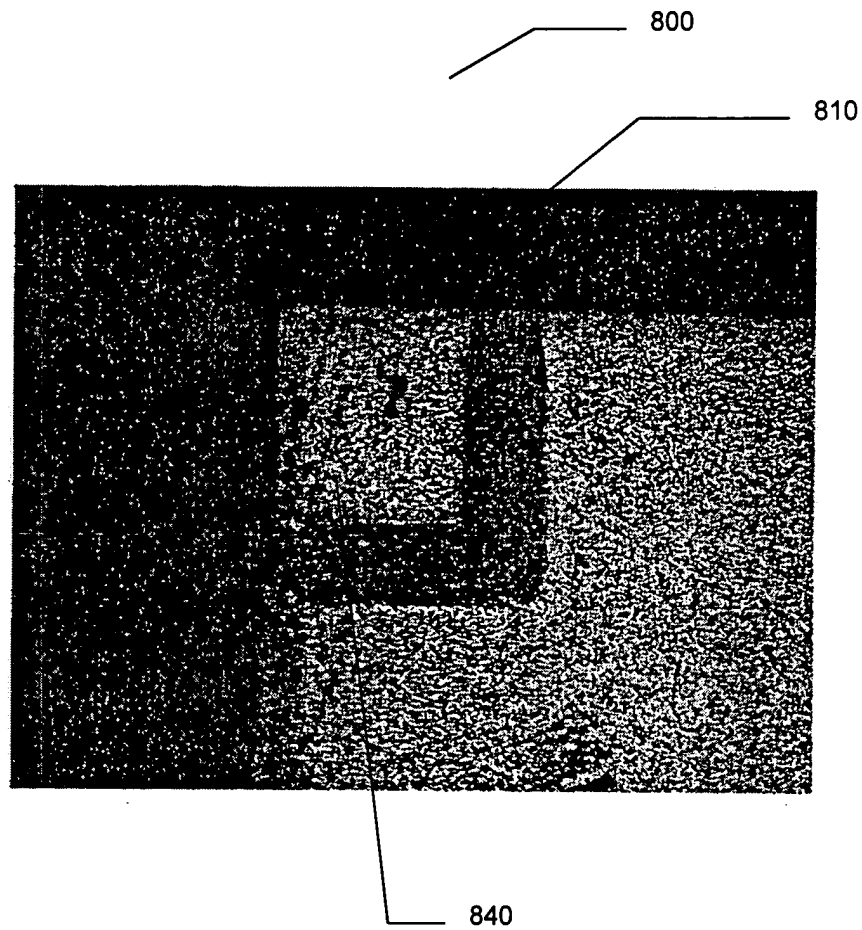


FIGURE 8

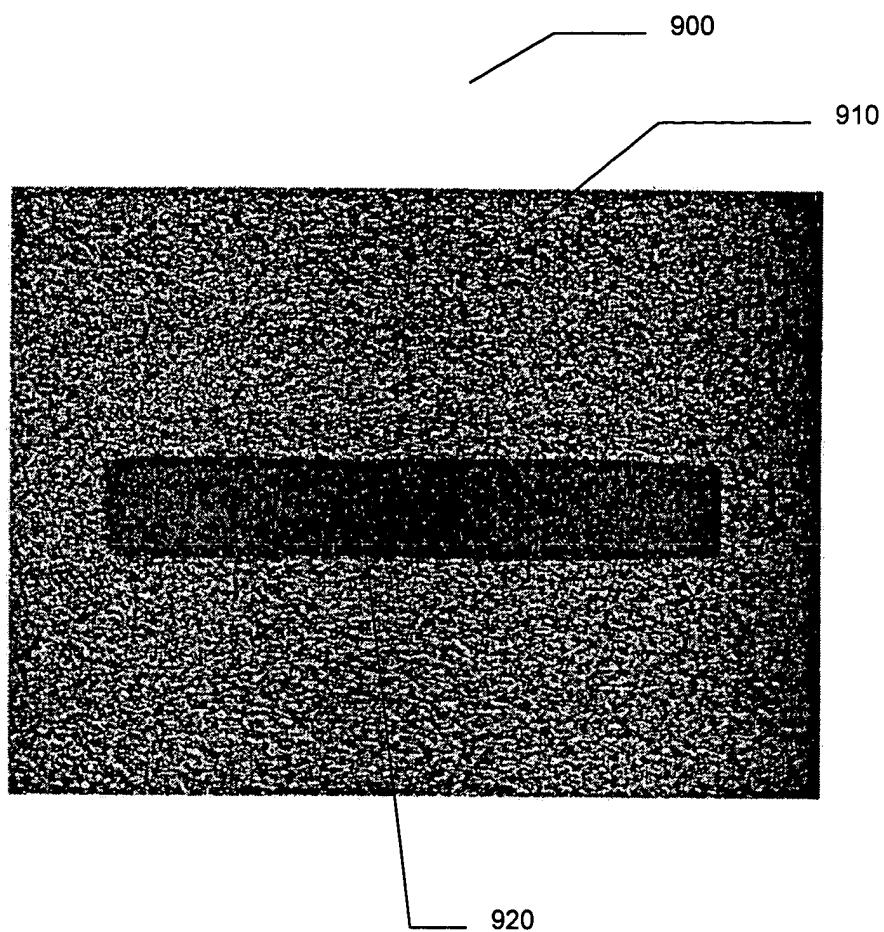


FIGURE 9

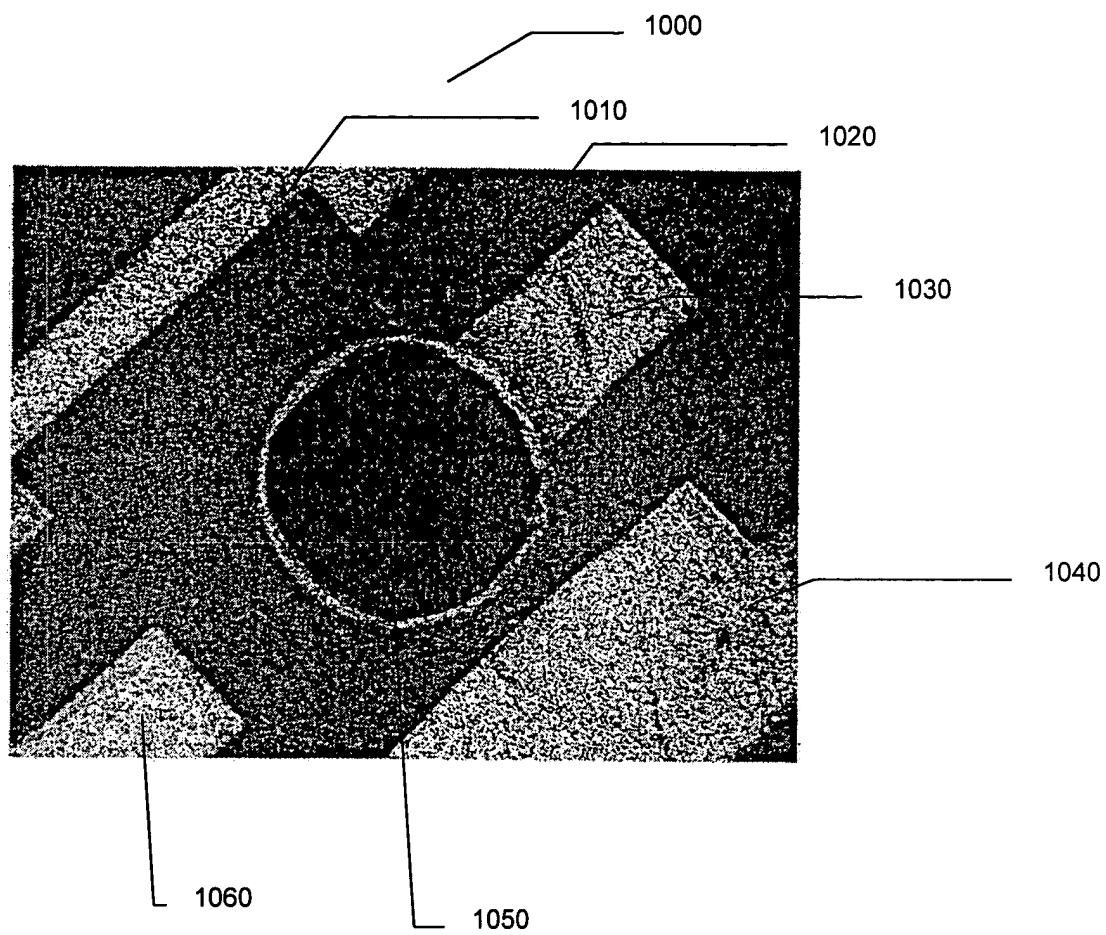


FIGURE 10

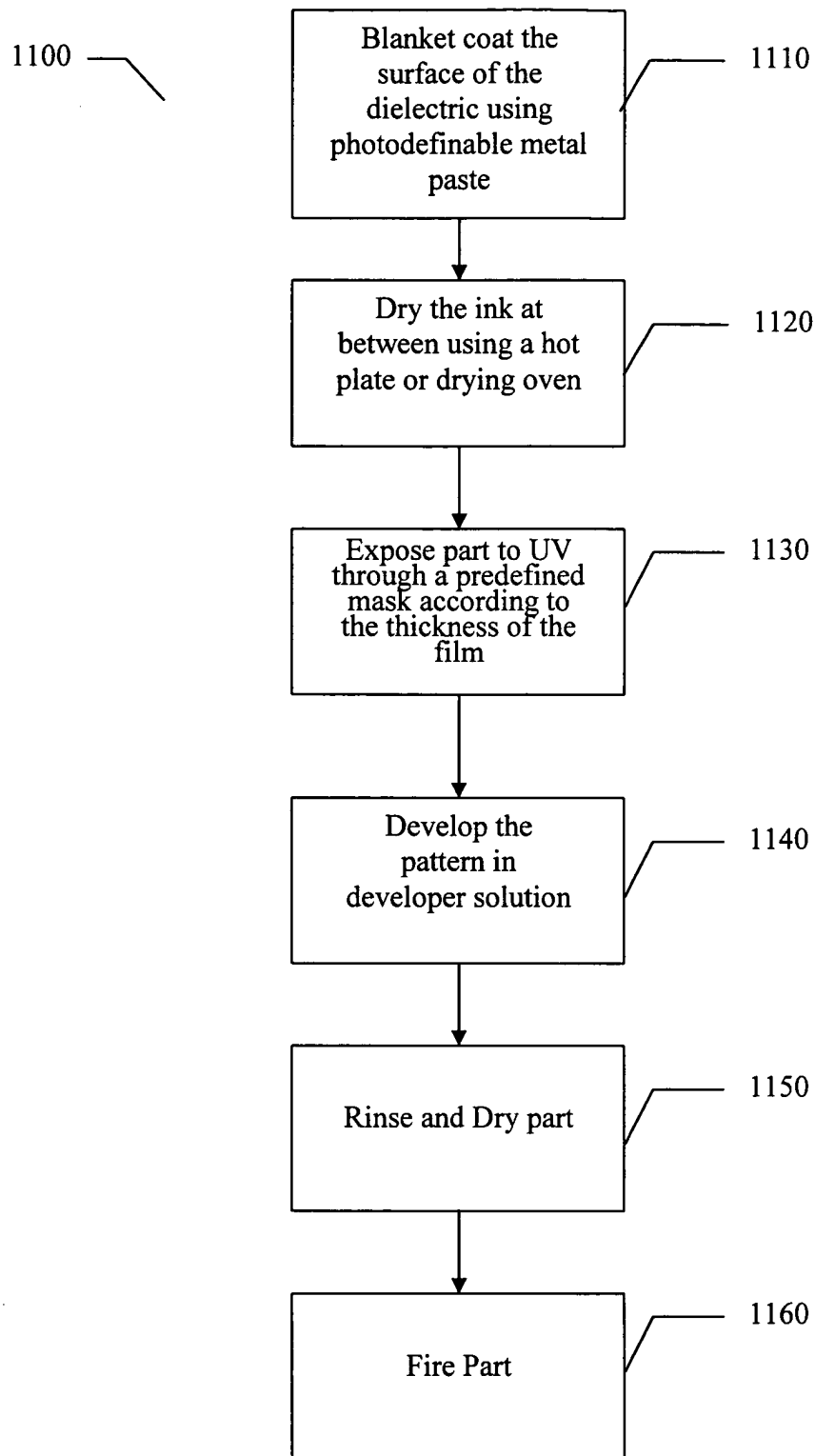


FIGURE 11

Process Steps	Photo-Define	Screen-Print	Etching	Typical Semi-conductor patterning	Laser Patterning
Apply wet metal	Yes	Yes	Yes	No	Yes
Drying of metal/photoresist	Yes	Yes	Yes	Yes	Yes
Exposing of metal or photoresist	Yes	No	Yes	Yes	No
Developing of metal or photoresist	Yes	Yes	Yes	Yes	No
Firing of Metal	Yes	Yes	Yes	No	Yes
Further trimming to obtain correct dimensions (not RF trimming)	No	Yes limited in dimensions	No	No	Limited to laser spot size
Vacuum Metallization (limited in deposition thicknesses)	No	No	No	Yes	No
Chemical Etching	No	No	Yes	Yes	No
Post Annealing/Cleaning	No	Yes	Yes	Yes	Yes

FIGURE 12